

46-415 Economy Version

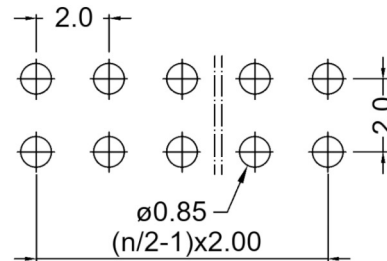
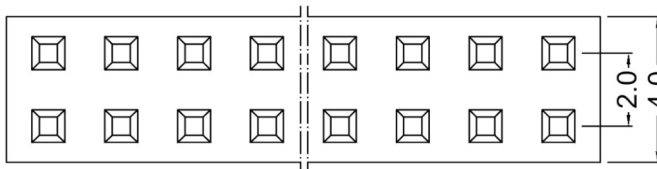
Buchsenleisten RM 2,00mm, gerade, 2-/4-reihig - BH 9,35mm
 Female Headers, 2.00mm Pitch, Straight, 2/4 Rows – 9.35mm Profile

Technische Daten / Technical Data

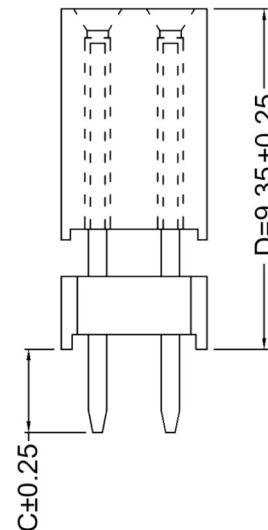
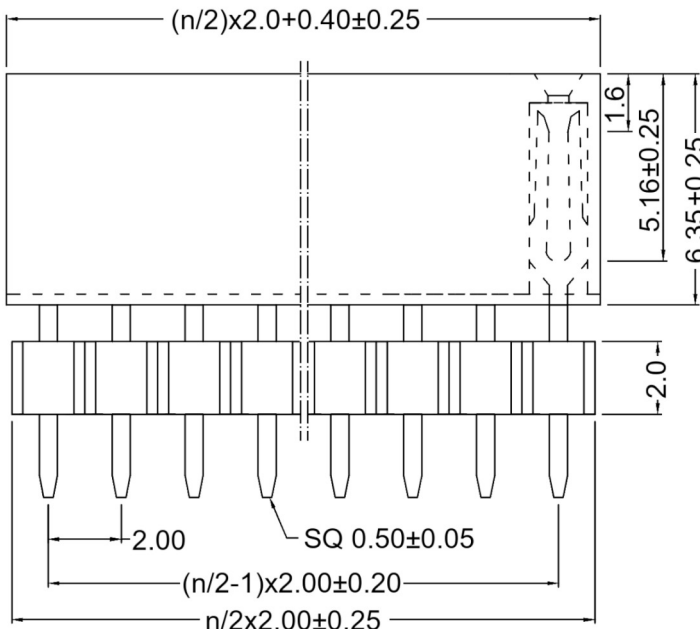
Isolierkörper	Thermoplast, nach UL94 V-0
<i>Insulator</i>	<i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial	Kupferlegierung
<i>Contact Material</i>	<i>Copper alloy</i>
Kontaktoberfläche	Au über Ni
<i>Contact Surface</i>	<i>Au over Ni</i>
Durchgangswiderstand	< 20 mΩ
<i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
<i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit	500 V AC
<i>Test Voltage</i>	<i>500 V AC</i>
Nennstrom	2 A
<i>Current Rating</i>	<i>2 A</i>
Temperaturbereich	-40 °C ... +105 °C
<i>Temperature Range</i>	<i>-40 °C ... +105 °C</i>
Verarbeitung	230 °C für 30-60 Sekunden (260 °C für 10 Sekunden)
<i>Processing</i>	<i>230 °C for 30-60 seconds (260 °C for 10 seconds)</i>



Gabelkontakte für Vierkantstifte 0,50mm.
 Fork contacts accept 0.50mm square pins.



Recommended P.C.B Layout (Top Side)
 (PCB BOARD TOLERANCE ±0.05)



Series

46-415

Contacts*

044

004-080 Zweireihig
 Double row

Rows

2

2 Zweireihig
 Double row

Dimensions*

10

10 C=2,28 D=9,35mm
 20 C=11,99 D=9,35mm
 99- Kundenspezifisch
 Customer-specific

Plating

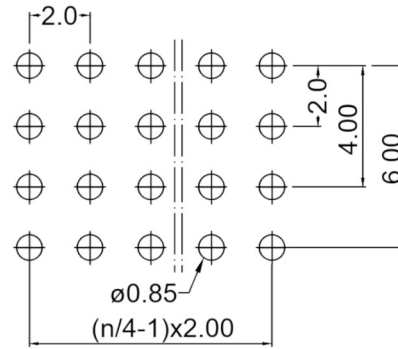
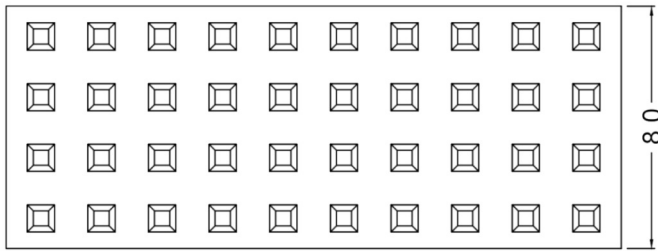
00

00 Vergoldet
 Gold plated

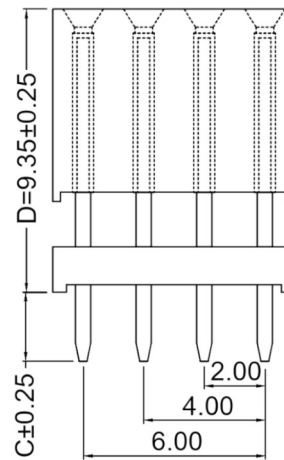
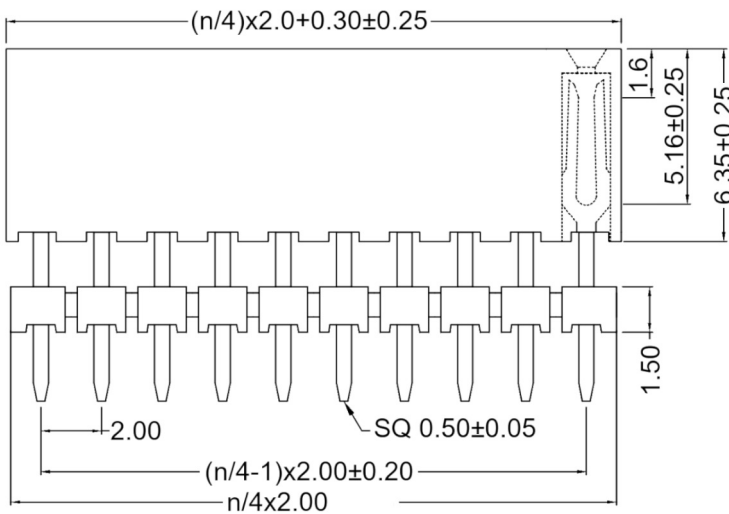
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Buchsenleisten RM 2,00mm, gerade, 2-/4-reihig - BH 9,35mm

Female Headers, 2.00mm Pitch, Straight, 2/4 Rows – 9.35mm Profile



Recommended P.C.B Layout (Top Side)
(PCB BOARD TOLERANCE ± 0.05)



Series

46-415

Contacts*

120

012-160 Vierreihig
Four rows

Rows

4

4 Vierreihig
Four rows

Dimensions*

10

10 C=2,28 D=9,35mm
20 C=11,99 D=9,35mm
99- Kundenspezifisch
Customer-specific

Plating

00

00 Vergoldet
Gold plated

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

